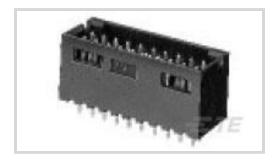
5-103168-2 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-103168-2 PCB Mount Header, Vertical, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded



Connector & Contact	Terminates To
---------------------	---------------

Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded					
PCB Mount Orientation	Vertical					
Number of Positions	8					
Number of Rows	2					
Board-to-Board Configuration	Parallel					
Electrical Characteristics						
Insulation Resistance	5000 MΩ					
Dielectric Withstanding Voltage (Max)	750 Vrms					
Body Features						
Connector Profile	Standard					
Primary Product Color	Black					
Contact Features						
Mating Square Post Dimension	.64 mm[.025 in]					

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PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]				
Contact Shape & Form	Square				
Contact Underplating Material	Nickel				
PCB Contact Termination Area Plating Material	Tin				
Contact Base Material	Phosphor Bronze				
Contact Mating Area Plating Material	Gold				
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]				
Contact Type	Pin				
Contact Current Rating (Max)	3 A				
Termination Features					
Square Termination Post & Tail Dimension	.64 mm[.025 in]				
Termination Post & Tail Length	3.18 mm[.125 in]				
Termination Method to Printed Circuit Board	Through Hole - Solder				
Mechanical Attachment					
Mating Retention	With				
Mating Retention Type	Detent Window				
Mating Alignment	With				

Mating Alignment Type	Polarization					
PCB Mount Retention	Without					
PCB Mount Alignment	Without					
Connector Mounting Type	Board Mount					
Housing Features						
Centerline (Pitch)	2.54 mm[.1 in]					
Housing Material	Thermoplastic					
Dimensions						
Row-to-Row Spacing	2.54 mm[.1 in]					
PCB Thickness (Recommended)	1.4 mm[.055 in]					
Usage Conditions						
Housing Temperature Rating	Standard					
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]					
Operation/Application						
Circuit Application	Signal					

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Industry Standards

Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	184
Packaging Type	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
•	
•	Compliant
For compliance documentation, visit the product page on TE.com>	Compliant Compliant
For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Wave solder capable to 240°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



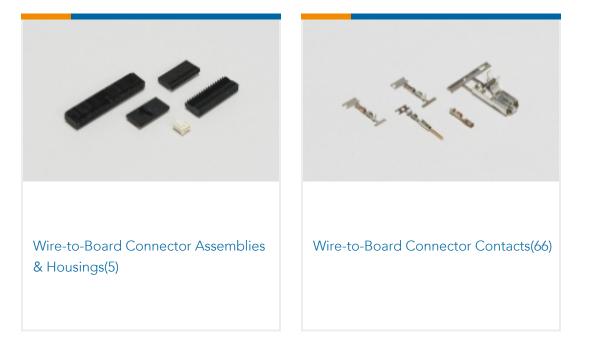




Also in the Series AMPMODU Headers



FCB Connector Mounting(1)	FCB Connector Shrouds(1)		FCD Latches, Locks & Retainers(2)

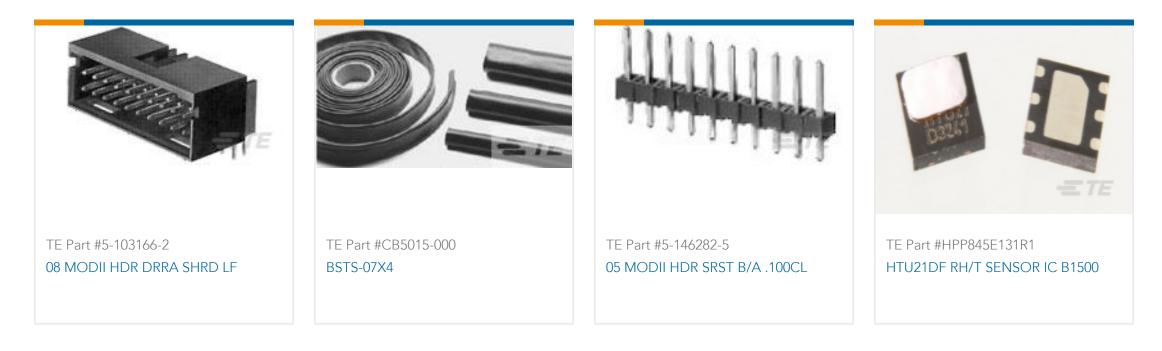


Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





Documents

Product Drawings 08 MODII HDR DRST SHRD .100CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-103168-2_M.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-2_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-103168-2_M.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

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